



Universität Hamburg
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CHyN
Centre for Hybrid Nanostructures

Atomic layer deposition of tantalum oxide

- a new material for coating cavities

TFSRF2024

19.09.2024

Marco Voige - on behalf of the SRF R&D Team Hamburg

Reducing losses

How can we improve cavities?

Improvement of SRF cavities

Idea: Getting rid of Nb_2O_5 (native oxide)

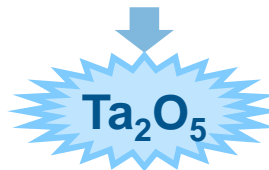
Removing
 Nb_2O_5

Baking



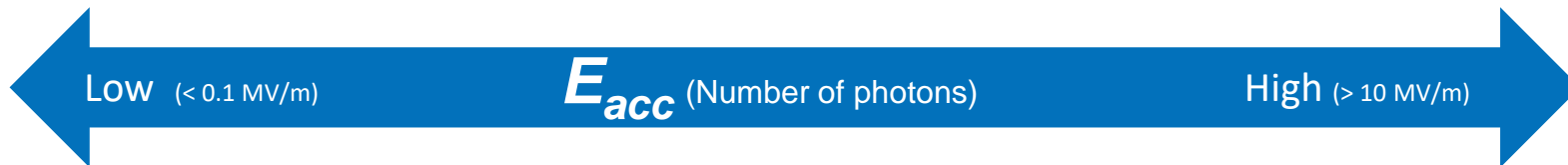
Stop Nb_2O_5 from
regrowing

Surface passivation



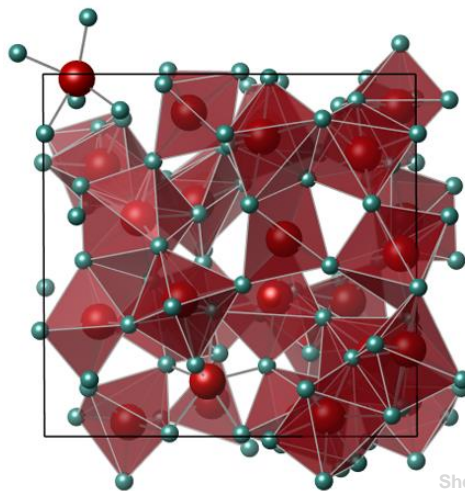
Nb₂O₅ as the potential cause of field losses

How can we improve cavities? Surface passivation



Cause of field losses

Two-Level Systems
Activation energy is taken from the rf field



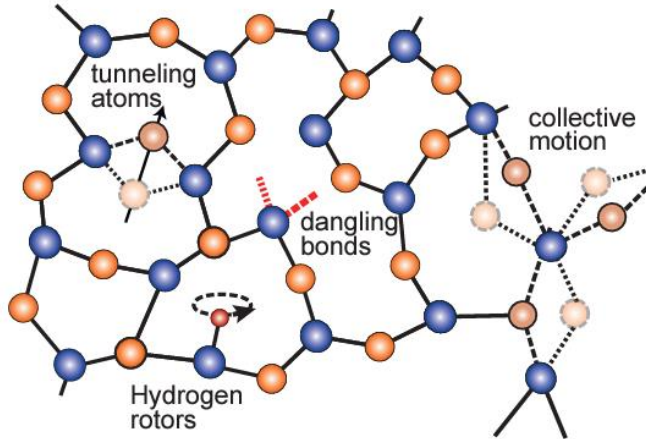
Magnetic impurities
Spin B-Field breaking Cooper pairs



Dangling bonds result in **Two-Level Systems (TLS)**

Why do amorphous materials lead to losses?

TLS-Variations



C. Müller et al. Reports on Progress in Physics, 82(12), 124501
Schematic representation in an arbitrary amorphous material

Local defects

Dangling bonds

Unsatisfied valence electron bonds

Missing spin compensation

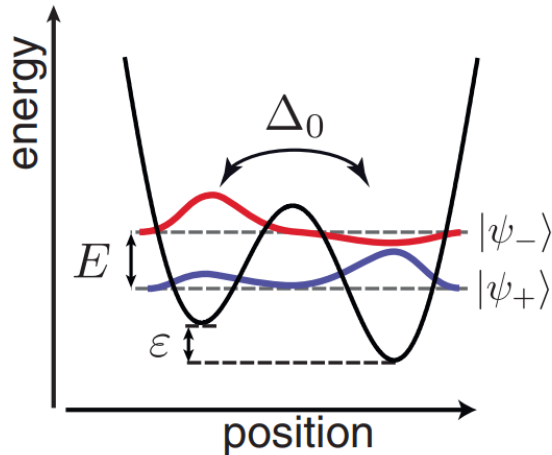
Metastable system

TLS

Losses due to **Two-Level Systems (TLS)**

Quantum systems between two stable energy levels

Standard tunneling model



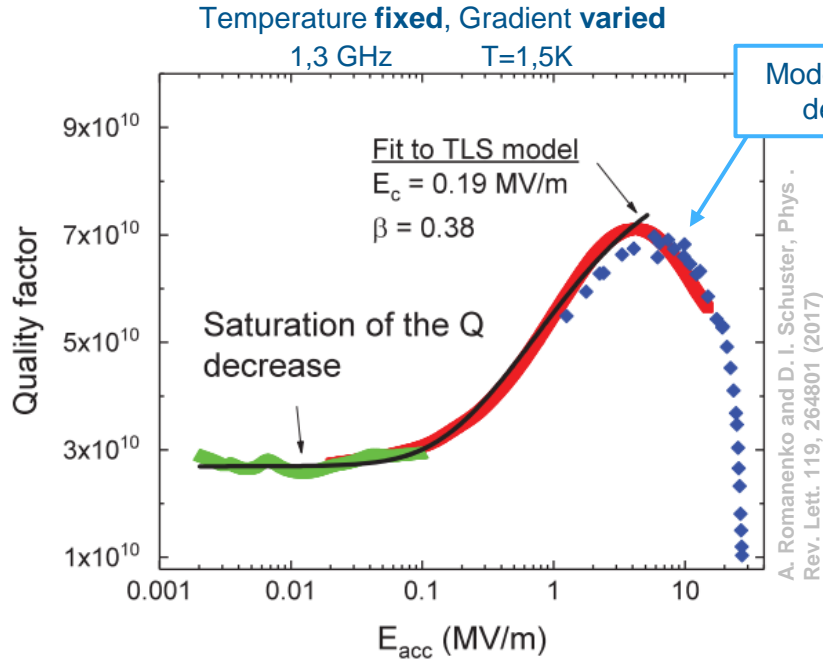
C. Müller et al. Reports on Progress in Physics, 82(12), 124501

Quantum system that can tunnel between two potential minima separated by a barrier

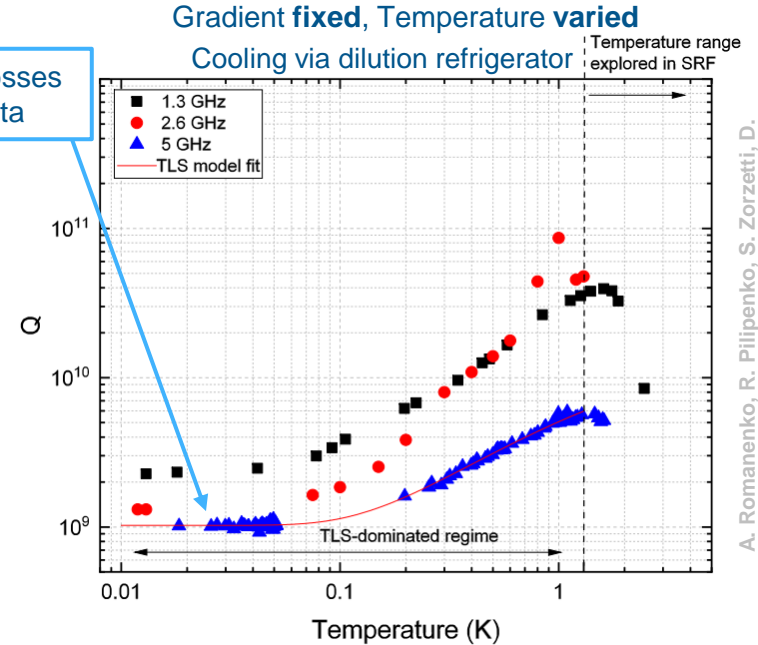
Activation energy taken from rf field!

- Thermal activation is suppressed at low temperatures / governed by quantum tunneling
- Random atomic arrangements
→ wide distribution of pot. barrier heights
→ large range of switching rates / eigenenergies

TLS as the cause of *Low Field Q-Slope (LFQS)*



Model of TLS losses describes data



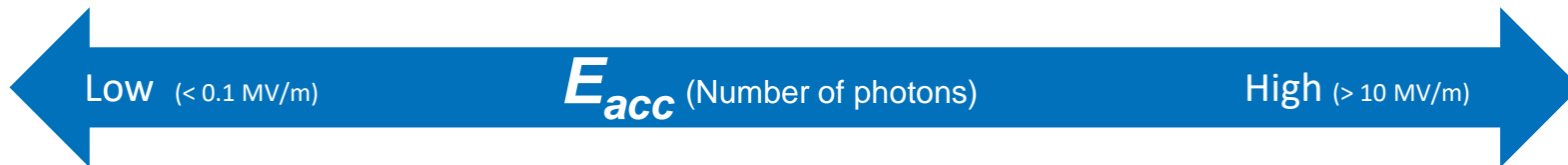
A. Romanenko, R. Pijipenko, S. Zorzetti, D. Frolov, M. Awida, S. Posen, A. Grassellino, arXiv:1810.03703

Surface resistance only residual resistance, no BCS losses

Qubits: absorption of energy by TLS when tunneling between states results in noise / decoherence

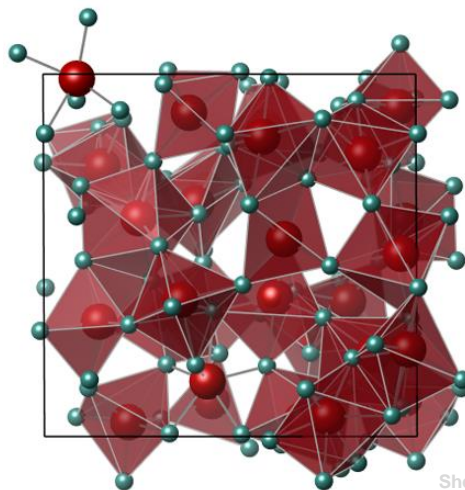
Nb₂O₅ as the potential cause of field losses

How can we improve cavities? Surface passivation



Cause of field losses

Two-Level Systems
Activation energy is taken from the rf field

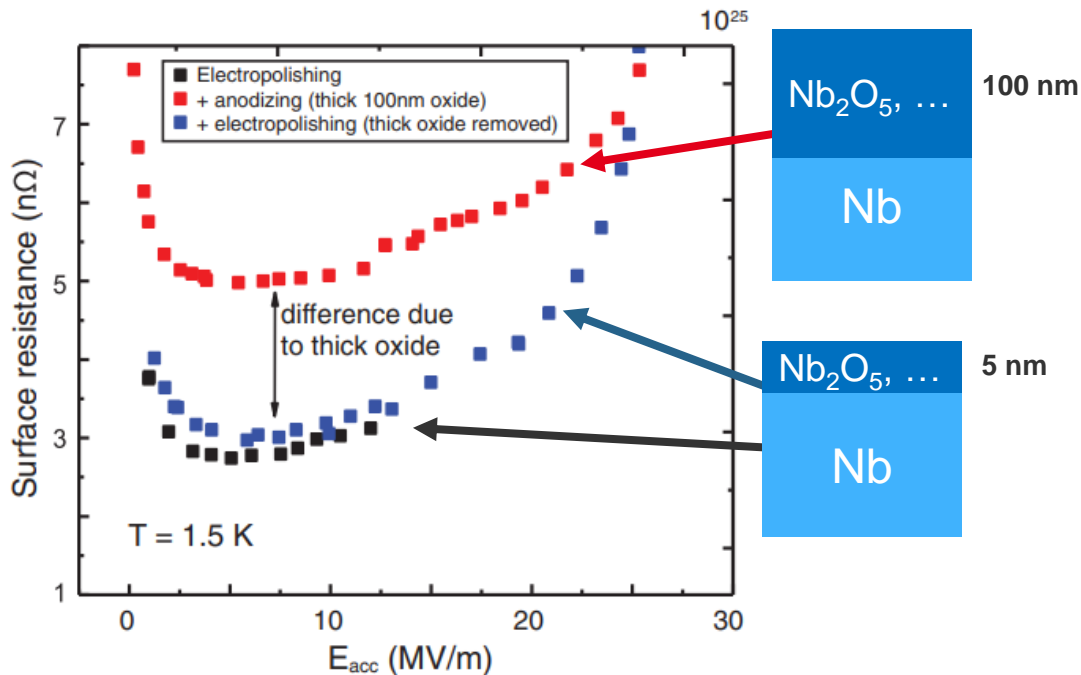


Magnetic impurities
Spin B-Field breaking Cooper pairs

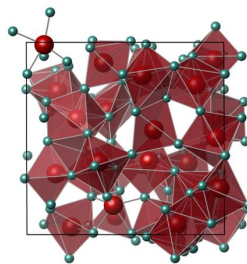


Magnetic impurities affect R_s

How can we improve cavities? Surface passivation



A. Romanenko and D. I. Schuster, Phys. Rev. Lett. 119, 264801 (2017)



Sheridan, E., et al., arXiv preprint arXiv:2111.1684, 2021

Nb_2O_5 is amorphous

Local non-stoichiometric

Unpaired Valence-electrons

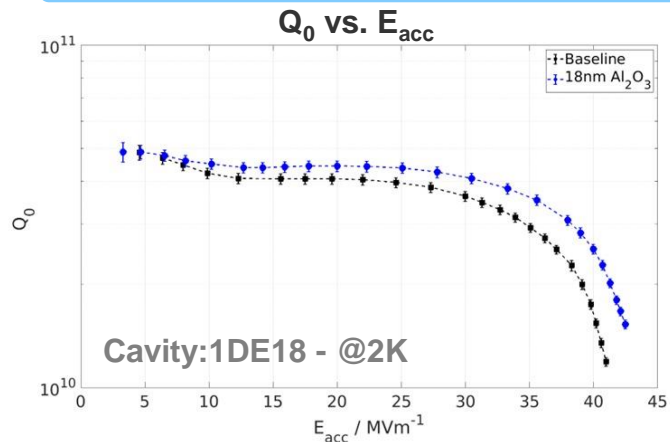
Magnetic Impurities

R_s affected

Coating / Passivation of the cavity surface

How do we prevent Nb_2O_5 from growing?

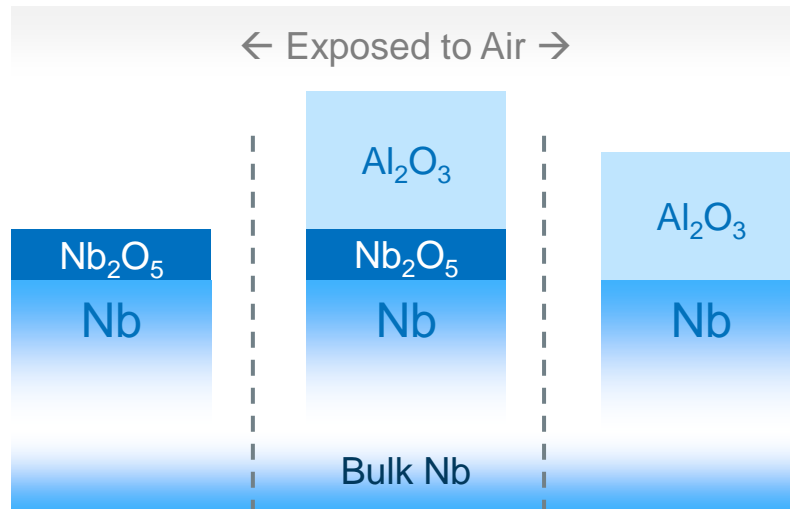
ALD on cavity already performed with Al_2O_3



Insulator alone does not affect quality

+

Insulator prevents new Nb_2O_5 from forming

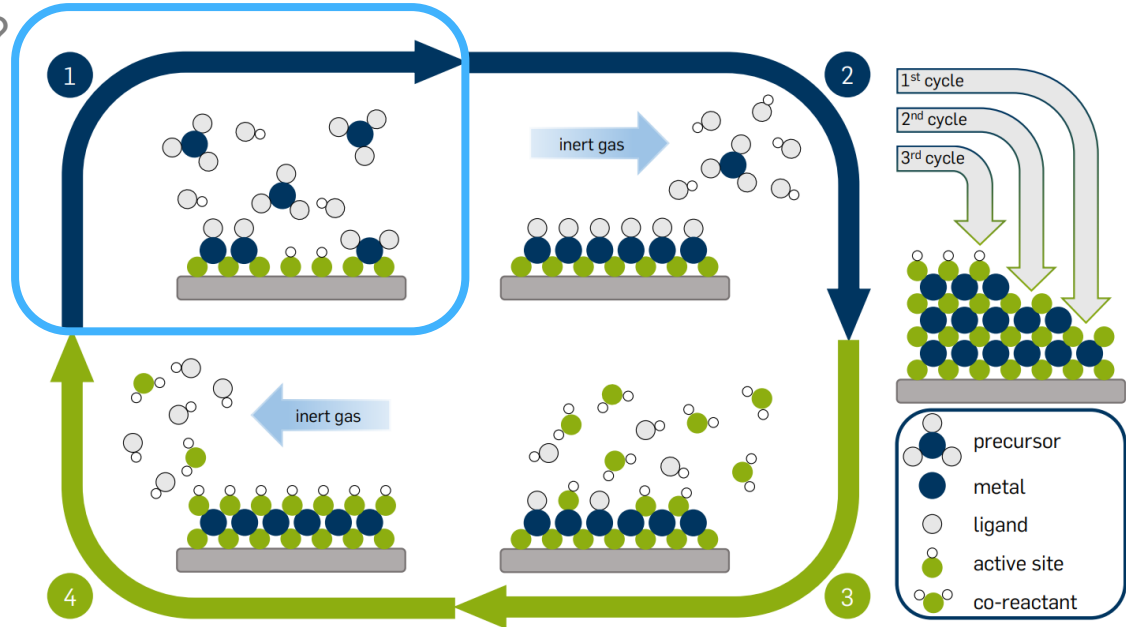


Baking removes the Nb_2O_5 -layer!

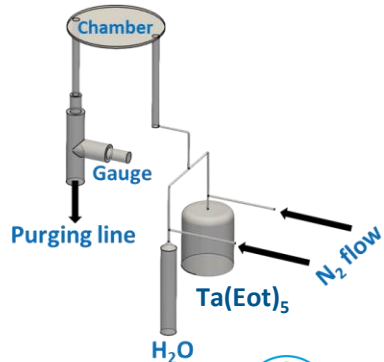
<i>ex-situ</i>	Baseline / Å	After Coating / Å	After baking / Å
Nb_2O_5	20	18	-
Al_2O_3	-	172	170

Thermal ALD basics

How does one coat a cavity?



Schematic layout of the system



L. Mai, (2020), DOI:10.13154/294-7658.

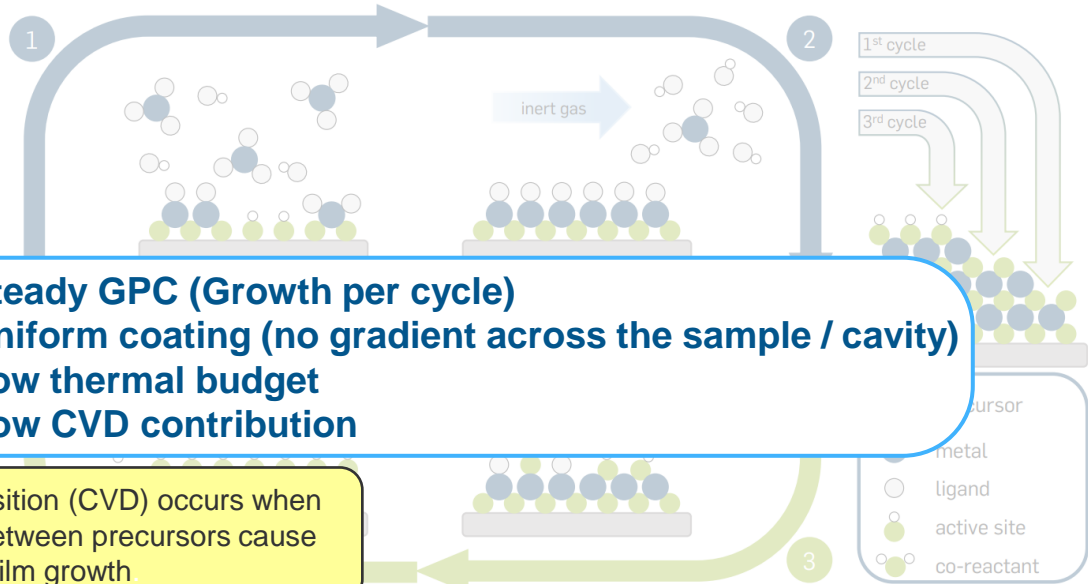
→ Thermal ALD requires two chemicals, one precursor: $Ta(Eot)_5$, one co-reactant: H_2O

ALD enables precise and uniform coatings on high aspect ratio substrates

Thermal ALD basics

How does one coat a cavity?

Schematic layout of the system



Goal of the optimisation

- Steady GPC (Growth per cycle)
- Uniform coating (no gradient across the sample / cavity)
- Low thermal budget
- Low CVD contribution

Chemical Vapor Deposition (CVD) occurs when undesired reactions between precursors cause uneven film growth.

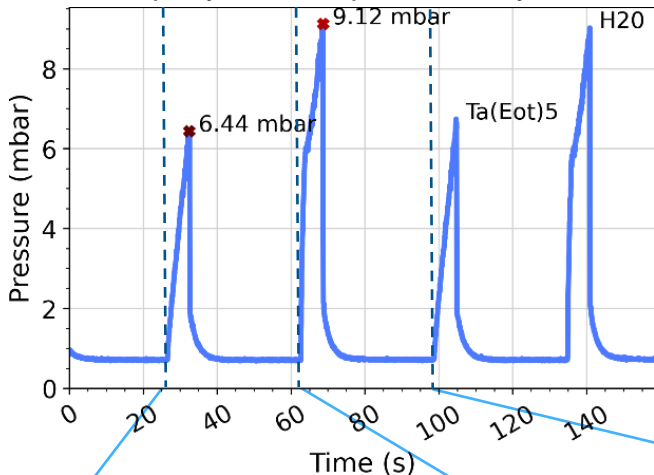
L. Mai, (2020), DOI:10.13154/294-7658.

→ thermal ALD requires two chemicals, one precursor: $Ta(Eot)_5$, one co-reactant: H_2O

Optimisation of the ALD recipe – insufficient deposition

What have we done so far to use Ta_2O_5 ?

Exemplary vacuum profile - 2 Cycles



Process as started

Not enough deposition /
unsteady GPC!

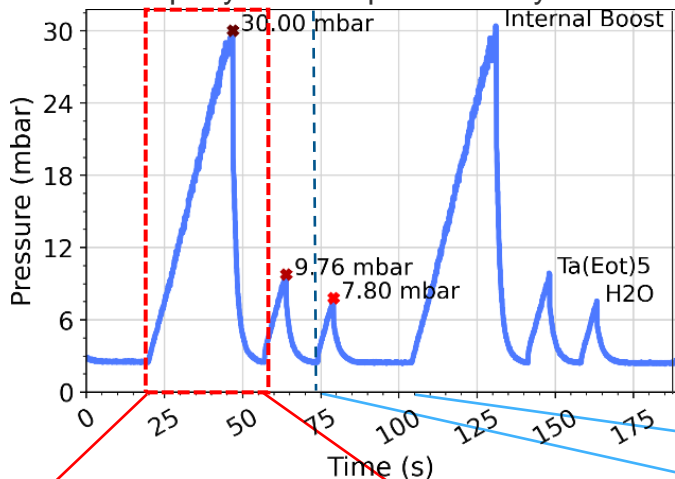
Problem: vapor pressure of the precursor is too low

Ta(Eot)5				H2O					
Pulse (s)	Exposure (s)	Purge (s)	Temp (°C)	Pulse(s)	Exposure (s)	Purge (s)	Temp (°C)	Process Temp. (°C)	N2-Flow (SCCM)
0.5	5	20	190	0.5	5	20	20	220	20

Optimisation of the ALD recipe – initial boost

What have we done so far to use Ta_2O_5 ?

Exemplary vacuum profile - 2 Cycles



Process with initial boost

Enough deposition /
steady GPC!

Internal boost corrects low vapor pressure of the precursor

Internal Boost				Ta(Eot)5				H2O					
Purge (s)	Exposure (s)	Pulse (s)	Purge(s)	Pulse (s)	Exposure (s)	Purge (s)	Temp (°C)	Pulse(s)	Exposure (s)	Purge (s)	Temp (°C)	Process Temp. (°C)	N2-Flow (SCCM)
5	25	2	10	2	5	10	190	0.1	5	20	20	220	20

Optimisation of the ALD recipe – parameter variation

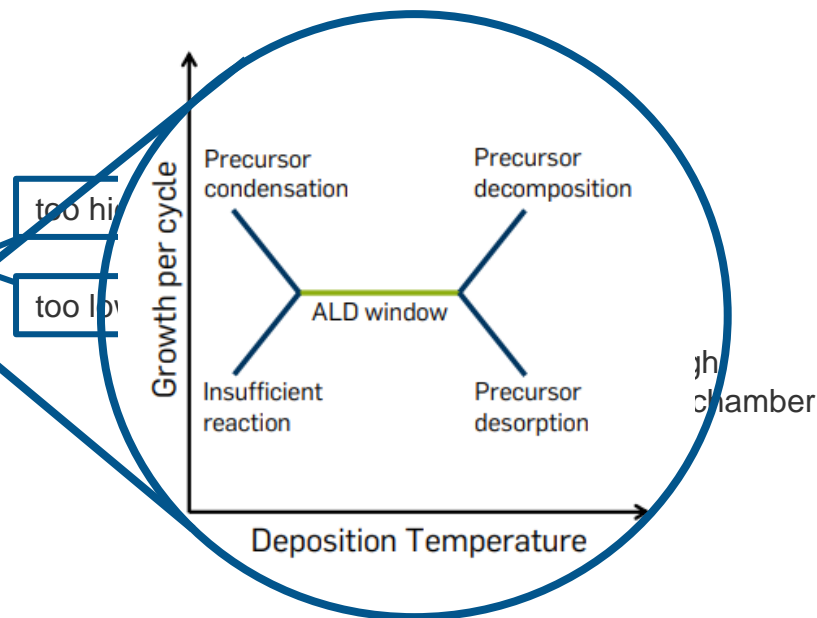
What are we currently working on to use Ta_2O_5 ?

To obtain the final parameters, the individual parameters must be varied in measurement series

→ Find the ALD window

Which parameters are to be varied:

- Ta precursor temperature ~150-190°C
- Deposition temperature ~ 170-220°C
- Water pulse, exposure and purge time
- Ta pulse, exposure and purge time
- Initial boost exposure time
- N2 flow rate



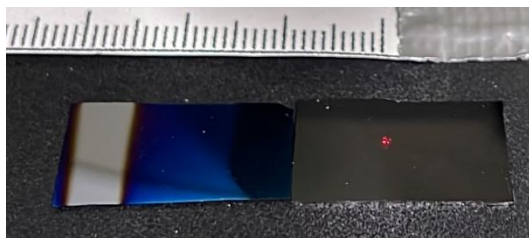
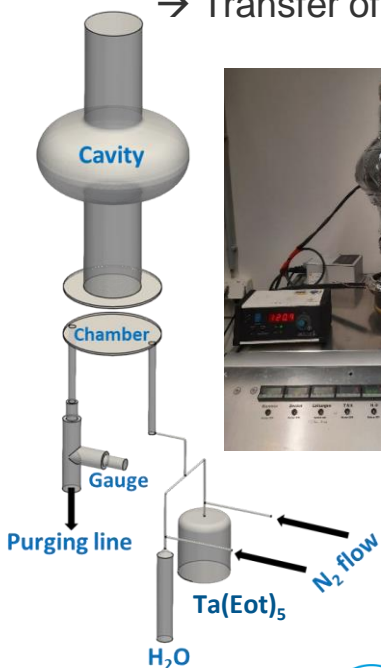
L. Mai, (2020), DOI:10.13154/294-7658.

Optimisation of the ALD recipe – GPC study

What are we currently working on to use Ta_2O_5 ?

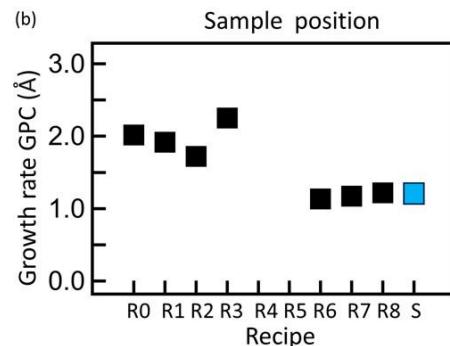
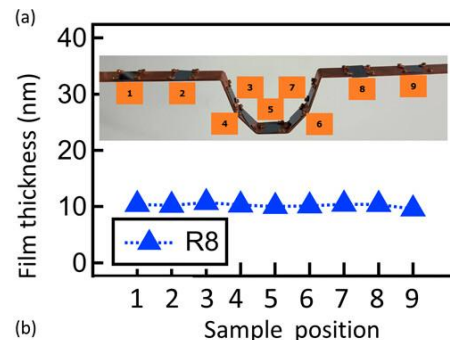
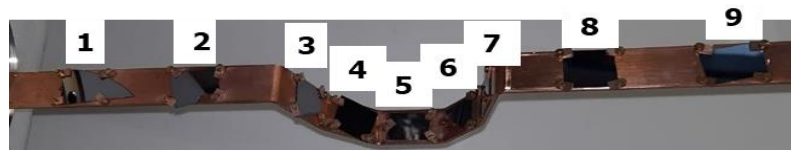
→ Transfer of the recipe from planar samples to 2D/ 3D cavity structure

Deyu, Getnet, et. al, Chem. Mater. 2024, 36, 6, 2846-2856



Silicon sample after coating with Ta_2O_5

Silicon sample before coating



GPC for various coatings already done with Al_2O_3 in the dummy cavity

Optimisation of the ALD recipe – current recipe

What are we currently working on to use Ta_2O_5 ?

Internal Boost				Ta(Eot) ₅			H2O			N2-Flow (SCCM)
Purge (s)	Exposure (s)	Pulse (s)	Purge(s)	Pulse (s)	Exposure (s)	Purge (s)	Pulse(s)	Exposure (s)	Purge (s)	
5	30	2	10	2	5	10	0.1	5	20	20

Temperatures (°C)					
Ta(Eot) ₅	H ₂ O	Chamber	Lid/Cavity	Valves	Exhaust
190	20	200	200	160	120



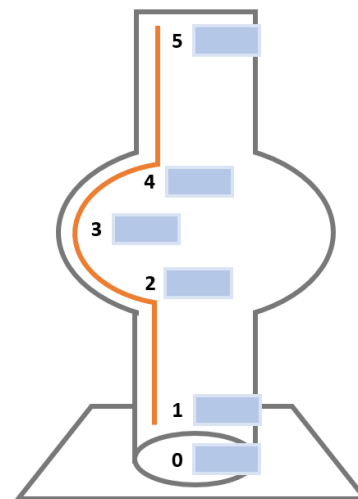
Simple chamber for plain Si-Samples

- 1000 Cycles
- GPC 0.3 Å/Cycle
- CVD share <25% (0.07 Å/Cycle)



Dummy Cavity for Si-Samples

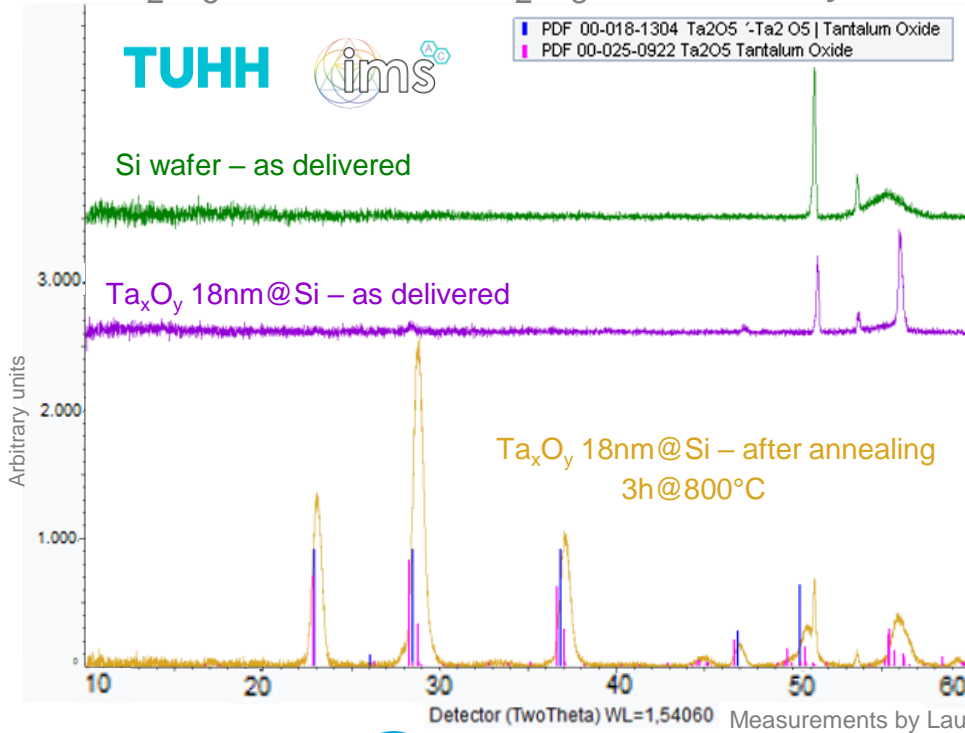
- GPC
- CVD share



Measured thicknesses across the dummy cavity

Ta₂O₅ instead of Al₂O₃ – crystallisation

Ta₂O₅ better than Al₂O₃ the industry standard?



Ta₂O₅ crystallizes at 800°C – Al₂O₃ needs >1000°C

- Nb annealing at 800°C is a standard recipe
- better order means less TLS

Nb₂O₅ dissolves above 250°C

- Ta₂O₅ passivates Nb after annealing
- Ta₂O₅ less prone to TLS than Nb₂O₅

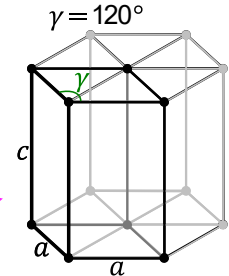
After annealing 3 main peaks

→ 23°, 29°, 37° that match with Ta₂O₅

Patterns:

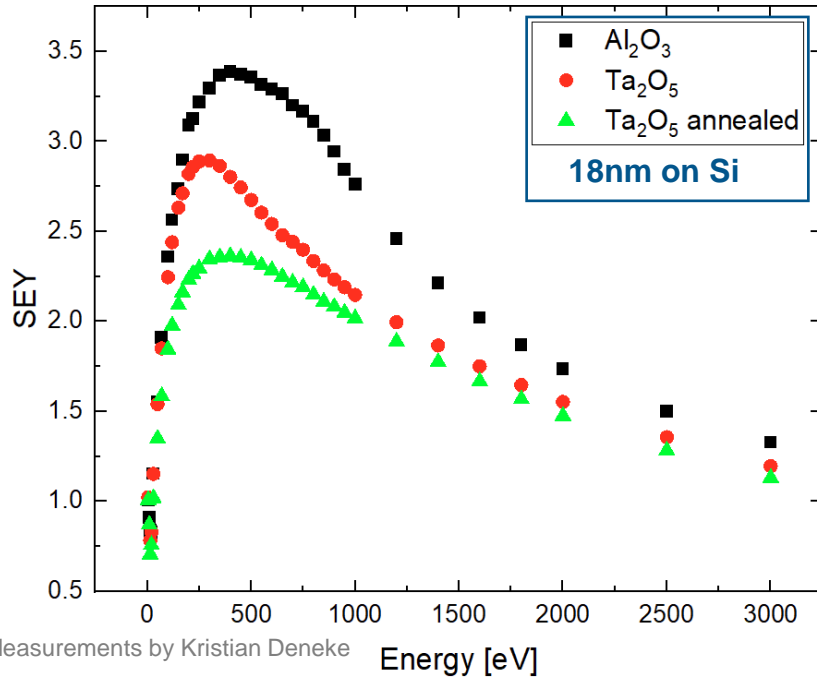
00-018-1304 – hexagonal

00-025-0922 – orthorhombic



Ta₂O₅ instead of Al₂O₃ – field emission

Is Ta₂O₅ better than the industry standard?



Al₂O₃ prone to field emission due to higher secondary electron yield (SEY)

→ Measurements of our layers show a significant reduction of SEY (Nb = 2.2)

Future activities

What needs to be done in order to use Ta_2O_5 to coat cavities?

-Coat a cavity

-HPR Test (High pressure rinsing)

→ Can the coatings withstand the HPR?

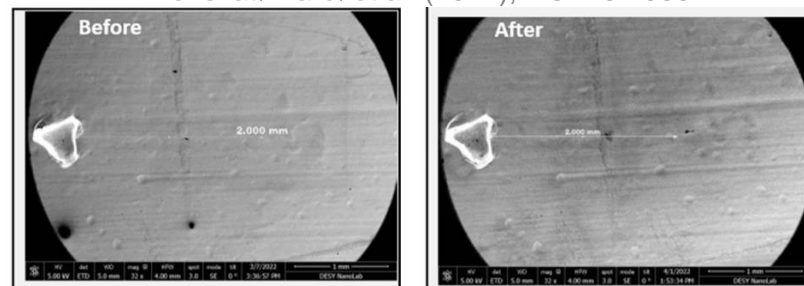
-Morphology Test

How does the crystallinity of Ta_2O_5 change after annealing at different temperatures?

-Passivation Test

How well does Ta_2O_5 passivate the inner surface of a cavity?

Wenskat, Marc, et al. (2022), DOI:10.1088



Exemplary SEM images of a Al_2O_3 -coated Nb-Sample before and after HPR

Summary

- Ta_2O_5 as potential material for improving SRF cavity performance beyond the niobium limit.
- Ta_2O_5 provides effective passivation, reducing Two-Level Systems (TLS)
- Ongoing process optimization to achieve uniform coating with optimal Layer Growth
- Further testing to confirm Ta_2O_5 's suitability for coating a single-cell cavity

Ta_2O_5 shows strong potential as a coating material to enhance SRF cavity performance by reducing losses and enabling superior surface passivation through optimized ALD processes.

Contact: marco.voige@desy.de

Backup-Slides

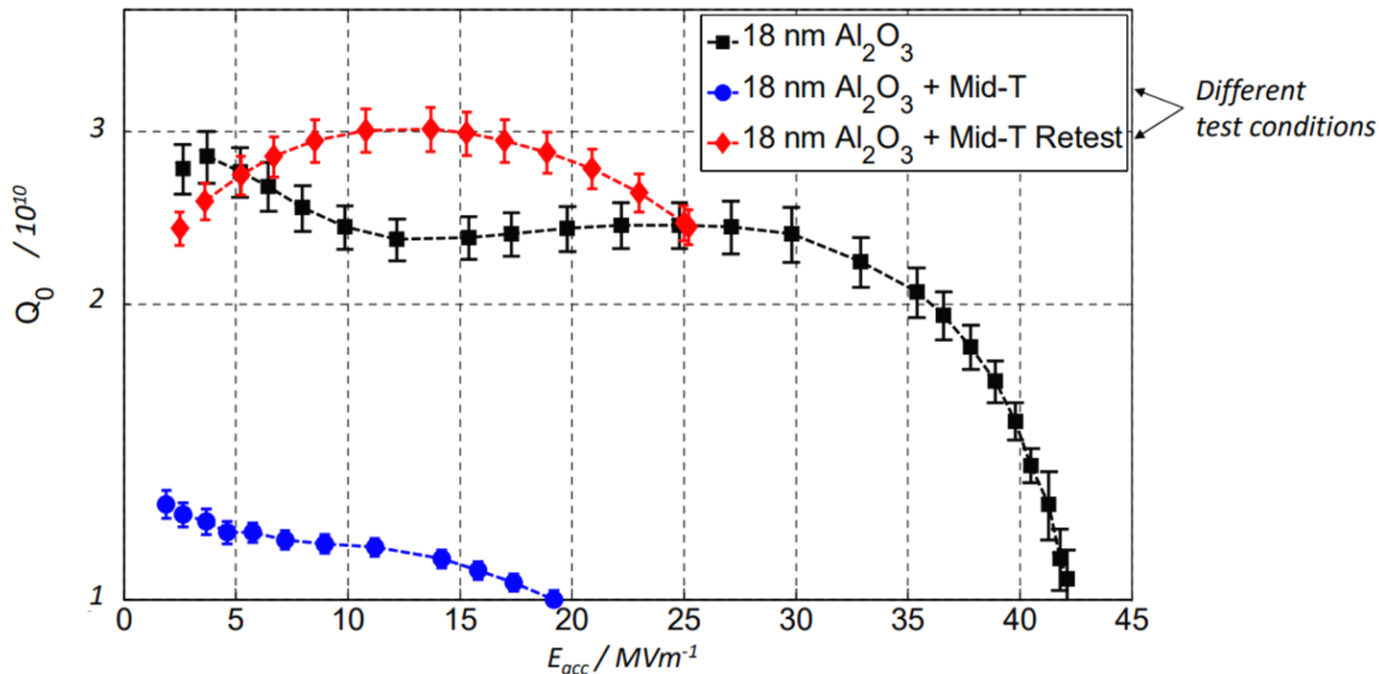
Atomic layer deposition of tantalum oxide a new material for coating cavities

19.09.2024

Marco Voige - on behalf of the SRF R&D Team Hamburg

Mid-T heat treatment of a coated cavity

Wenskat - TUIBA02



Reduced R_{BCS} beyond regular mid-T cavities

Wenskat - TUIBA02

Bate - MOPMB022

Ghanbari - MOPMB021

- $R_{BCS}(2K) \approx R_S(2K) - \underbrace{R_S(1.5K)}_{\approx R_{res}}$
- R_{BCS} smaller than for other mid-T cavities
3nΩ @ 2K
- R_{res} is higher due to mid-T
before: 3nΩ
after: 6nΩ
- Why is R_{res} higher?
 - sensitivity higher for mid-T cavities → increased R_{flux} ?
 - agrees with low Q_0 in first test after mid-T
 - 120°C before mid-T may affect R_{res} negatively

